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H1N5820_{thru} H1N5822

3.0 AMPS, SCHOTTKY BARRIER RECTIFIERS

Features

- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability

Mechanical Data

- Cases: DO-201AD molded plastic.
- Epoxy: UL 94V-0 rate flame retardant.
- Lead: Axial leads, solderable per MIL-STD-202, Method 208 guaranteed.
- Polarity: Color band denotes cathode end.
- High temperature soldering guaranteed: 250°C/10 seconds/.375"(9.5mm) lead lengths at 5 lbs., (2.3Kg) tension.
- Weight: 1.10 grams.

Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Type Number	H1N5820	H1N5821	H1N5822	Units	
Maximum Recurrent Peak Reverse Voltage	20	30	40	V	
Maximum RMS Voltage	14	21	28	V	
laximum DC Blocking Voltage 20 30 40					
Maximum Average Forward Rectified Current 0.375"(9.5mm) Lead Length @ TL=90°C		Α			
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)		А			
Maximum Instantaneous Forward Voltage @ 3A	0.475	0.5	0.525	V	
Maximum Instantaneous Forward Voltage @ 9A	0.85	0.9	0.95	V	
Maximum DC Reverse Current At Rated DC	2 (@ Ta=25°C)			mΑ	
Blocking Voltage	20 (@ Ta=100°C)			mΑ	
Typical Thermal Resistance (Note 1) R θ JA		°C /W			
Typical Junction Capacitance (Note 2)		pF			
Operating Temperature Range Tj		°C			
Storage Temperature Range TSTG		°C			

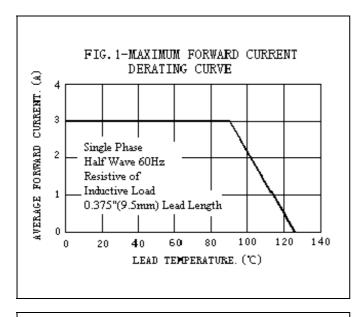
Note 1: Thermal resistance from junction to ambient vertical P.C. Board Mounting, 0.375"(9.5mm) lead length.

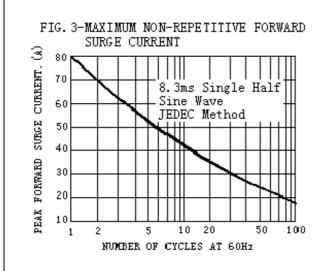
Note 2: Measured at 1Mhz and applied reverse voltage of 4V D.C.

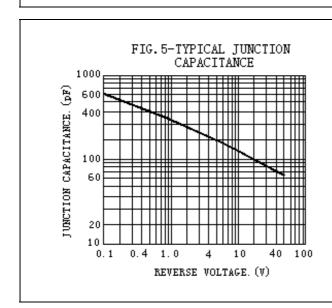
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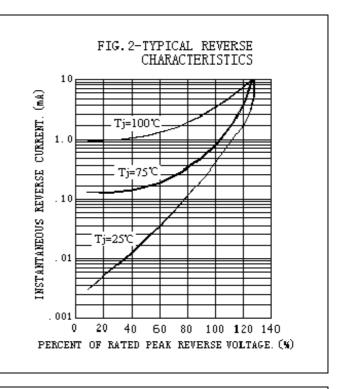
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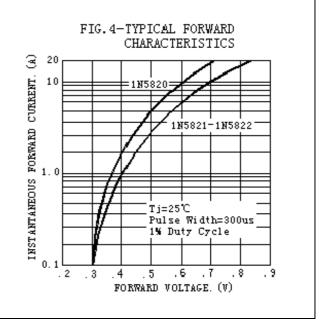
Characteristics Curve







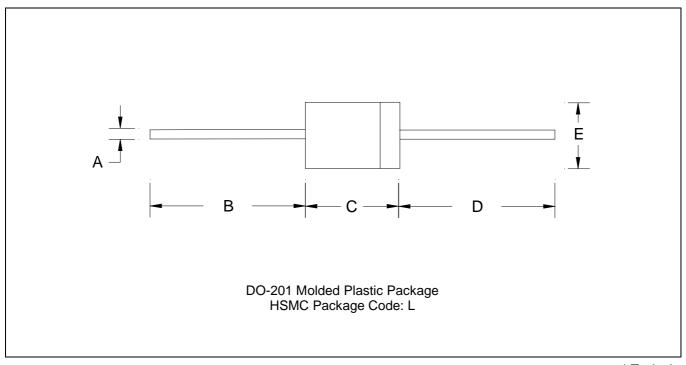




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DO-201 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.	וווט	Min.	Max.	Min.	Max.
Α	0.0472	0.0512	1.20	1.30	D	1.0000	-	25.40	-
В	1.0000	•	25.40	•	Е	0.1890	0.2087	4.80	5.30
С	0.2835	0.3740	7.20	9.50					

Notes: 1.Dimension and tolerance based on our Spec. dated May 28,1998.

- 2. Controlling dimension : millimeters.
- 3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
- 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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